

for  
comment

widely. Further, use of ArF excimer laser light (wavelength 193 nm) has been started, and use of F<sub>2</sub> laser light has been attempted. --

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Please substitute the paragraph beginning at page 3, line 14, and ending on page 4, line 3, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

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9/3

-- However, it is practically difficult to purge the entire path of exposure light. Particularly, in the neighborhood of a reticle or a wafer, there is a stage which is movable. Therefore, it is difficult to separate only the light path from the surrounding ambience and to purge the same. Further, there are cases wherein the light path between adjacent units extends through a surrounding ambience. In addition, while there are optical elements provided at a light entrance port and a light exit port of each container, containing a unit of optical elements, the surfaces of these optical elements facing the surrounding ambience are exposed directly to the ambience and, therefore, depositions may be adhered to them. This leads to degradation of the optical performance, such as a decrease of illuminance, for example, and thus it causes a necessity of periodic washing or replacement. --

Please substitute the paragraph beginning at page 4, line 4, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

-- Particularly, one of optical elements of a projection optical system which is closest to a wafer is directly exposed to a gas produced from a resist. As a result, the transmission factor of it

decreases most. In order to avoid this, a gas may be caused to flow in one direction, along a space between a wafer and a lens, such as shown in Figure 2. Here, in exposure apparatuses, any fluctuation in an ambience is adversely influential to the imaging performance. Further, in scan type exposure apparatuses, since a stage moves, a gas from a resist is easily mixed. It is, therefore, very difficult to decrease the impurity concentration at the lens surface effectively. --

Please substitute the paragraph beginning at page 4, line 17, and ending on page 5, line 16, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

-- In these methods, a gas product from a wafer is rather conveyed to the lens surface, along the gas flow, such that sufficient contamination prevention is not attainable. Japanese Laid-Open Patent Application, Laid-Open No. 26038/1994 shows a method in which an inactive gas is supplied through a supply port provided on a stage, in parallel to a wafer and, simultaneously, a gas is supplied toward the wafer from the bottom end of a projection optical system, in parallel to the optical axis. This method has paid a particular note to an oxygen concentration in the space from the projection optical system to the wafer, but the efficiency itself regarding the contamination prevention at the bottom face of the projection optical system is not so good. Between a projection lens and the surface of a wafer, measurement light for measuring the imaging position passes. Any change in temperature or pressure of an ambience in the space through which the measurement light passes, leads to a measurement error, and this applies a large influence to the position adjustment for the wafer imaging position. Further, a

change in temperature or pressure of the ambience is also influential to the imaging performance.

For these reasons, the flow of a gas of a large flow rate or any fluctuation in pressure or temperature causes an error of the wafer position adjustment and degradation of the imaging performance. --

Please substitute the paragraph beginning at page 5, line 19, and ending on page 6, line 4, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

-- It is accordingly an object of the present invention to provide an optical structure and/or a method of preventing contamination of the same, in which a clean gas is supplied efficiently to the surface, or in the neighborhood thereof, of an optical element being isolated from a surrounding ambience, thereby to keep the surface clean and to prevent adhesion of depositions thereon. This assures minimization of the influence of the gas flow to the imaging performance and adjustment of the imaging position, for example, such that contamination of the optical element can be prevented with a very small amount of gas flow. --

Please substitute the paragraph beginning at page 9, line 19, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

-- In accordance with another aspect of the present invention, there is provided an exposure apparatus for illuminating a pattern with light from a light source and for projecting

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light from the pattern onto a surface to be exposed, said apparatus comprising: an optical structure as recited above, wherein the light from the light source is light of an ultraviolet region. --

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Please substitute the paragraph beginning at page 10, line 12, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

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-- In accordance with a yet further aspect of the present invention, there is provided an optical structure, comprising: an optical element; and a gas supplying means for supplying a gas to a surface of the optical element, wherein the gas supplied to the surface of the optical element defines a laminar flow at and adjacent to the surface of the optical element. --

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Please substitute the paragraph beginning at page 11, line 18, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

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-- The optical structure may further comprise gas supplying equipment having impurity removing means, for supplying a gas to said gas supplying means. --

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Please substitute the paragraph beginning at page 12, line 25, and ending on page 13, line 9, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

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-- The optical structure may further comprise (i) a plurality of optical elements, (ii) a plurality of gas supplying means disposed along a direction substantially perpendicular to a

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changed

direction in which the gas is to be supplied, (iii) a container isolated from a surrounding ambience, wherein said plurality of optical elements may be disposed at least at a light entrance surface and a light exit surface of said container, and (iv) a cover for covering the light entrance surface and/or the light exit surface of said container, wherein said plurality of gas supplying means may be provided inside said cover. --

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Please substitute the paragraph beginning at page 15, line 20, and ending on page 16, line 6, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

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9/9

-- In the preferred embodiments of the present invention to be described below, the arrangements described above are applied by which a gas which may contain only a very small quantity of impurities, causing depositions, can be blown against a limited portion of the surface of an optical element, facing a surrounding ambience, or can be caused to flow to produce a laminar flow. Thus, an ambience with a very small quantity of impurities can be produced adjacent to the surface of the optical element, and adhesion of deposition thereto can be suppressed. As a result, contamination of the surface of the optical element, facing the surrounding ambience, can be prevented efficiently. --

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Please substitute the paragraph beginning at page 16, line 13, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

GA10

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-- A gas supply port may be provided at one side of the lens surface while a gas discharging port may be disposed at the opposite side of the lens surface, so that a gas flows along the lens surface. This enables that a clean ambience is locally produced at the lens surface only by use of a small flow rate of the gas. --

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Please substitute the paragraph beginning at page 17, line 20, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

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GA11

-- However, one face of the top-most lens and one face of the bottom lens are exposed to be the ambience of the exposure apparatus chamber. In consideration of it, a plurality of gas supply ports 13 are provided around the bottom-most lens of the projection system, about the lens optical axis, to surround the lens. --

Please substitute the paragraph beginning at page 17, line 27, and ending on page 18, line 9, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

-- Gases 15 discharged from these gas supply ports flow along the lens surface toward the center of the lens. Adjacent to the center, the gases flow as a downward stream, and they are diffused. In order to produce an effective flow, the flow rate and the flow speed, for example, should be controlled. To this end, an optimum shape of the discharging port 15 as well as an optimum flow rate and pressure of the gas are determined in accordance with the shape and size of the lens, for example. --

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Please substitute the paragraph beginning at page 18, line 22, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

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-- Exposure apparatuses may be individually equipped with impurity removing devices such as filters. However, a gas supplied from a factory or experimental equipment, having an impurity removing function, may be used. --

Q12

Please substitute the paragraph beginning at page 18, line 27, and ending on page 19, line 10, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

-- The type of gas to be used may be chosen in accordance with the wavelength of ultraviolet rays, for example, to be used in the exposure apparatus. An atmosphere may be used where i-line or a KrF laser is used. When light of a shorter wavelength is used, an inactive gas such as nitrogen or He, for example, may be used. When an inactive gas is supplied directly from a commercially available high purity cylinder, for example, since substantially no impurity is contained therein, the impurity removing device may be omitted. --

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Please substitute the paragraph beginning at page 19, line 20, and ending on page 20, line 10, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

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Q13

-- A valve 14 for adjusting the flow rate of the supplied gas may be controlled so as to adjust the gas flow rate in accordance with the state of exposure operation. This enables a more

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effective supply of a clean gas to the lens surface. For example, during an alignment process, during an imaging position measuring process or during an exposure process, the flow of a gas applies a large influence to the imaging performance. Therefore, the gas flow rate should be restricted. On the other hand, during a wafer conveying process, for example, the gas flow can be increased. Thus, when a new wafer is conveyed onto a wafer stage, the supplying flow rate may be increased, thereby to effectively remove an impurity gas, produced from a resist, away from the lens. During the alignment and exposure process, the flow rate may be decreased to prevent adverse influence to the imaging performance. --

Please substitute the paragraph beginning at page 20, line 11, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

-- When a gas of the same type as that of the gas used inside the barrel can be used and caused to flow along the lens surface, as shown in Figure 3, the gas may be supplied from a gas discharging port of the projection barrel. --

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Please substitute the paragraph beginning at page 20, line 18, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

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Q14

-- Figure 4 is a schematic view of a second embodiment of the present invention. In the gas supplying method of the first embodiment, there may be cases wherein, depending on the size or shape of the lens, for example, the gas that flows from the lens to the wafer surface is diffused



of a resist gas. In consideration of it, as shown in Figure 4, a gas discharging port 17 may be provided below the supply port. This is effective to produce a gas flow. --

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Please substitute the paragraph beginning at page 21, line 1, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

-- Also, in this case, there may be a plurality of gas discharging ports disposed revolutionally symmetrically with respect to the optical axis, like the gas supply ports. --

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Please substitute the paragraph beginning at page 21, line 27, and ending on page 22, line 14, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

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Q115

-- A gas supply port 18 and a gas discharging port 20 are provided in the neighborhood of the bottom-most lens of the projection system, that is, the lens 3 closest to the wafer, and the lens surface of the barrel 22 at the top of the projection system, facing the chamber ambience side, such that a clean gas is caused to flow. As shown in Figure 5B, the gas supply port 18 is provided at one of lens side faces while the gas discharging port 20 is provided at the opposite lens side face, by which an effective gas flow is produced locally upon the lens surface. Particularly, plural gas supply ports and plural gas discharging ports may preferably be provided. On that occasion, a gas flows uniformly along the lens surface. --

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Please substitute the paragraph beginning at page 22, line 23, and ending on page 23, line 9, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

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916

-- A flow rate adjusting valve 19 may be used to adjust the flow rate and flow speed of the gas so that a laminar flow is produced. In this method, although the gas flow is only in one direction, the ambience at the lens surface can be effectively kept clean with use of only a limited flow rate of the gas. Therefore, the influence to the imaging performance or imaging position measurement is small. Further, there is an advantage that only a relatively narrow space is required. Moreover, since a gas flows only locally on the lens surface, in the case of a scan type exposure apparatus, the influence of resist gas diffusion due to the motion of the stage, for example, can be made small. --

Please substitute the paragraph beginning at page 23, line 10, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

-- Between a projection optical system and a wafer, a probe light for focus position measurement passes. If there occurs non-uniformness of pressure or temperature in the ambience through which the probe light passes, it causes a measurement error. In consideration of this, usually, a gas of the same type as that of the chamber ambience is used. In this embodiment, however, since the gas flow is stable, a gas having a refractive index different from that of the ambience gas may be used. For example, in a case wherein the chamber ambience is atmosphere, a nitrogen gas may be caused to flow. When the barrel inside space is purged by the same type of

gas, the same gas line may be used. If a different type of gas is to flow, a separate line is necessary. When the same gas line as that of the chamber ambience is used, since the gas must be sufficiently clean, gas purifying means such as a filter may be used, as required. --

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Please substitute the paragraph beginning at page 24, line 1, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

-- This embodiment is applicable not only to a projection system but also to a portion of a separate optical system such as an illumination system, for example, as shown in Figure 6. Figure 6 is a schematic and sectional view of an optical system, wherein an optical system 23 is accommodated inside a barrel 22 being isolated from a surrounding ambience. Along the optical path, the ambience is isolated by means of a seal glass 24 which comprises a parallel flat plate. The inside of the barrel is purged by a clean gas, through a gas supply port 25 and a gas discharging port 26. In order that a clean gas flows along the surface of the seal glass 24, being in contact with the surrounding ambience, a gas supplying port 27 is provided at one side face while a gas discharging port 28 is provided at the opposite side face. By adjusting the flow rate and the pressure, a gas is caused to flow along the seal glass surface. --

Please substitute the paragraph beginning at page 24, line 25, and ending on page 25, line 8, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.